

ABSTRACT

Disclosed in the present invention are a photonic integrated circuit chip and a silicon photonics integrated platform, aimed at implementing efficient coupling with common single-mode optical fibers by providing a specific waveguide structure on the photonic integrated circuit chip, without introducing a suspended structure, so that the overall structure has high mechanical stability, reliability tests for photonic integrated circuit chips under high temperature and high humidity conditions can be passed, and processes such as reflow soldering and through-silicon vias are feasible.

10 FIG. 15